

## IEC QUALITY ASSESSMENT SYSTEM (IECQ)

covering Electronic Components,

Assemblies, Related Materials and Processes For rules and details of the IECQ visit www.iecg.org

Schedule of Scope to Certificate of Conformity

## Approved Component - Capability

IECQ Certificate No.: IECQ-C BSI 14.0051

CB Certificate No.: E065/CA

Schedule Number: IECQ-C BSI 14.0051-S		<b>Rev No.:</b> 9	Revision Date	: 2017/11/08	Page 1 of 1
Test Report: CA TR 02 Issue 1 : February 1997					
Assessment Level : C					
Boards Types:		igid Multilayer igid double-sided with plated-through holes igid single and double-sided with plain holes			23 300-003 23 200-003 23 100-003
Base Materials:	Epoxide Woven Glass				
Board Size:	380 mm x 360 mm	Maximum		BS EN 123 100, BS EN 123 200	
	405 mm x 280 mm	Maximum		BS EN 123 200 BS EN 123 300	
Conductors:	Minimum width: Minimum spacing:	$\begin{array}{rrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrr$	•		
No. of Layers:	12 Maximum				
Plated-through hole diameter:	0.35 mm Minimum	drilled via h	nole		
Aspect Ratio:	4.6 : 1 Maximum				
Finishes:	*Hot Air Solder Levelling Liquid Photopolymer solder resist Legend; (Thermal Cured)				
Additional:	Buried via holes;	0.5mm drilled			

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